

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the first full paragraph on page 7 of the specification with the following amended paragraph:**

The solubility parameter as referred to herein means a strength at which molecular agglomerates gather. In the material of the molding die, in the case where the solubility parameter exceeds 8.5, wetting between the die and the sealant cured material becomes good so that mold release properties from the die becomes worse, and hence, such is not preferable. The solubility parameter has the units  $(\text{cal}/\text{cm}^3)^{1/2} \text{mol}^{-1}$ .